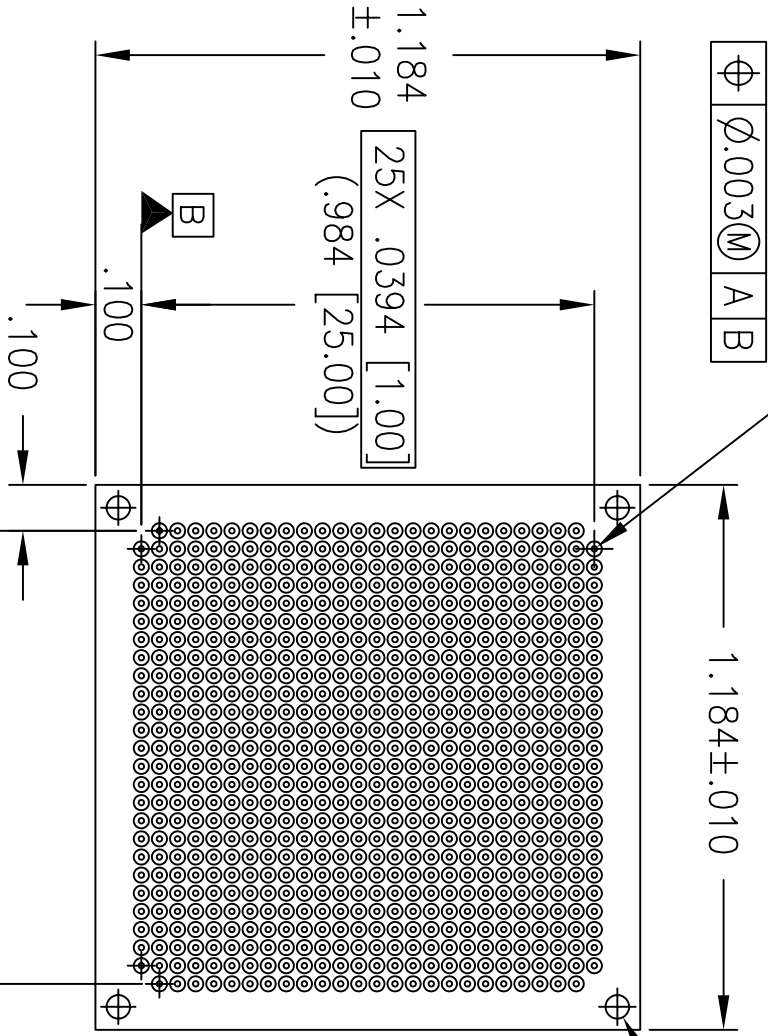


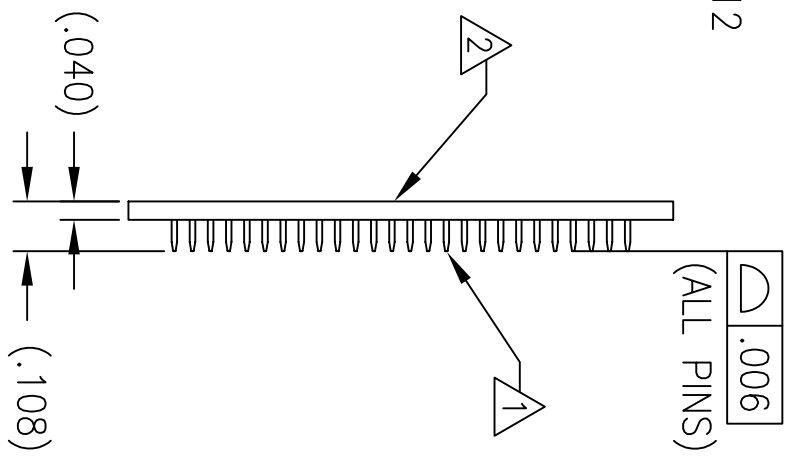
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REV	DESCRIPTION	EGN	DATE	APPROVAL
1	SALES RELEASE			

TOP VIEW



RS VIEW



NOTES:

- PINS  $\phi$ .0117  
MATERIAL: PHOSPHOR BRONZE.  
PLATING: HARD GOLD OVER NICKEL.
- INSULATOR MATERIAL: FR4.

CONTRACT NO.		TITLE	
DESIGNER	DATE	DESIGNER	DATE
CHECKER	DATE	CHECKER	DATE
PROCESS ENG.	DATE	PROCESS ENG.	DATE
UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES TOLERANCES: ANGLES: $\pm$ 1/64 FRACTIONS: $\pm$ .010 DECIMALS: .XXX $\pm$ .005 .XXXX $\pm$ .0005		<p>INTERCONNECT SYSTEMS INC. 708 VIA ALONDRA, CAMARILLO, CA 93012</p> <p>HIL0-BGA PIN BASE 26 X 26, 672 PINS 1mm PITCH</p>	
SCALE	DRAWING NO.	SCALE	DRAWING NO.
A	HLP-260672-B-10	N/A	HLP-260672-B-10
FINISHED ASST: HLP-260672-B-10		FINISHED ASST: HLP-260672-B-10	
SHEET 1 OF 1		SHEET 1 OF 1	

ASIZE 4 3 2 1